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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of:

5 Jin-Yuan Lee et al.

Examiner: THAI, LUAN C

Serial No.: 10/055,499

Art Unit: 2891

10 Filed: January 22, 2002

Docket No.: MEGP0012USA

For: INTEGRATED CHIP PACKAGE
STRUCTURE USING ORGANIC
SUBSTRATE AND METHOD OF
MANUFACTURING THE SAME

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RESPONSE TO FINAL OFFICE ACTION

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COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, Virginia 22313-1450

25 Dear Sir:

The Final Office Action mailed Aug. 9, 2006 has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks. A continued examination is politely requested.

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